

**Amendments to the Claims:**

This listing of claims replaces all prior versions, and listings, of claims in the application:

Claim 1 - 11 (Cancelled)

Claim 12 (New) A cup type plating apparatus, comprising:

a plating tank in which a wafer is plated with a plating solution, said plating tank having an opening at a top side of the plating tank on which the wafer to be plated is to be placed;

a liquid-supply tube provided at a bottom center of the plating tank for supplying the plating solution to the wafer;

an anode provided in the plating tank;

a cathode connected to the wafer; and

stirring means beneath a target surface of the wafer for forcibly stirring the plating solution supplied into the plating tank to form a liquid-flow channel in the plating solution in an upward flow from said liquid-supply tube, and the plating solution contacts said target surface of plating of said wafer to complete plating.

Claim 13 (New) The cup type plating apparatus according to claim 12, wherein said means for stirring comprises:

a donut-shaped disc provided with stirring blades for forcibly altering the flow of plating solution around and beneath the periphery of the target surface of plating; and

a driving mechanism capable of holding said disc parallel to the target surface of plating and rotating said disc perpendicularly to the upward flow of the plating solution supplied from the liquid-supply tube.

Claim 14 (New) A cup type plating apparatus, comprising:  
a plating tank in which a wafer is plated by a plating solution, said plating tank having an opening at a top side of the plating tank on which the wafer to be plated is to be placed;  
a liquid-supply means for supplying the plating solution to the wafer;  
an anode provided in the plating tank;  
a cathode connected to the wafer; and  
means for stirring the plating solution beneath a target surface of the wafer to form a liquid-flow channel in an upward flow from said liquid-supply means such that the plating solution contacts said target surface of said wafer to complete plating.

Claim 15 (New) The cup type plating apparatus according to claim 13, wherein said means for stirring comprises:  
a donut-shaped disc provided with stirring blades for forcibly altering the flow of plating solution around beneath the periphery of the target surface of plating; and  
a driving mechanism capable of holding said disc parallel to the target surface of plating and rotating perpendicularly to the upward flow of the plating solution supplied from the liquid-supply means.